

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(encapsulant adj mixture).ti.	USPAT	OR	ON	2005/03/18 14:38
L2	0	(encapsulant with mixture).ti.	USPAT	OR	ON	2005/03/18 14:33
L3	192	(encapsulant).ti.	USPAT	OR	ON	2005/03/18 14:33
L5	4857	epoxy.ti.	USPAT	OR	ON	2005/03/18 14:38
L6	99	5 and (catalyst.ti.)	USPAT	OR	ON	2005/03/18 14:43
L7	211	epoxy.ti. and adhesive.ti.	USPAT	OR	ON	2005/03/18 14:45
L8	306197	bis(4-glycidyloxyphenyl)methane	USPAT	OR	ON	2005/03/18 14:46
L9	44	glycidyloxyphenyl adj methane	USPAT	OR	ON	2005/03/18 14:46
L10	42	9 and epoxy	USPAT	OR	ON	2005/03/18 14:50
L11	13	isopropylidenediphenol adj diglycidyl adj ether	USPAT	OR	ON	2005/03/18 15:25
L12	603	epoxy with (boron adj trifluoride)	USPAT	OR	ON	2005/03/18 15:25
L13	21	12 and encapsulant	USPAT	OR	ON	2005/03/18 15:25
S1	162	polystyrene and (diphenyl adj phosphine)	USPAT	OR	ON	2005/03/17 15:48
S2	1	S1 and encapsulant	USPAT	OR	ON	2005/03/17 15:51
S3	15	S1 and semiconductor	USPAT	OR	ON	2005/03/17 12:35
S4	252	polystyrene and (diphenyl adj phosphine)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 12:39
S5	90	S4 not S1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 12:36
S6	9	polystyrene with (diphenyl adj phosphine)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 14:04
S7	1726	encapsula\$4 and (epoxy with catalyst) and (heat or temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 15:54

S8	435	S7 and ((encapsula\$4 or mold\$3 or underfill) with (die or chip or microelectronic or IC or wafer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 15:55
S9	371	S8 and (epoxy with (cure or cures or cured or curing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 15:56
S10	23	S9 and ((epoxy with liquid) and (catalyst with solid))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 16:31
S12	2832	438/106.ccls. or 438/112.ccls. or 438/124.ccls. or 438/126.ccls. or 438/127.ccls.	USPAT	OR	ON	2005/03/18 14:26
S13	343	S12 and (die with mold)	USPAT	OR	ON	2005/03/17 16:38
S14	373	S12 and ((epoxy adj resin) and mold)	USPAT	OR	ON	2005/03/17 16:38
S15	86	S12 and ((epoxy adj resin) with mold)	USPAT	OR	ON	2005/03/17 16:55
S16	23	S12 and ((epoxy adj resin) with catalyst)	USPAT	OR	ON	2005/03/17 16:39
S17	36	S12 and ((epoxy adj resin) with (heat and curing))	USPAT	OR	ON	2005/03/17 17:17
S18	1	("6309916").PN.	USPAT	OR	OFF	2005/03/17 17:17